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| Notice of References Cited | Application/Control No. 09/840,500 | Applicant(s)/Patent Under Reexamination TSAI, ROGER S. | |
| | Examiner Thomas H. Stevens | Art Unit 2123 | Page 1 of 1 |

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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